

# Bill of Materials

TI DESIGNS

RS-485 Power over Bus

TIDA-00527

Item	Qty	Reference	Value	Manufacturer	Manufacturer Part Number	PCB Footprint
1	1	C3	0.1u	Any	Any (10V+ Rating)	0402
2	1	C4	DNI	Any	Any (10V+ Rating)	0402
3	1	C5	1u	Any	Any (10V+ Rating)	0402
4	1	C6	1u	Any	Any (10V+ Rating)	1206
5	2	C7,C8	10u	Any	Any (10V+ Rating)	0805
6	1	JMP1	2 Pin Berg Jumper	Samtec	HTSW-150-08-G-S	HDR_THVT_1X2_100
7	4	JMP2,JMP3,JMP4,JMP5	3 Pin Berg Jumper Single Side	Samtec	HTSW-150-08-G-S	HDR_THVT_1X3_100
8	2	JMP6,JMP7	Header 2x2	Samtec	HTSW-150-08-G-D	HDR_THVT_2X2_100
9	2	JMP8,JMP9	Header 2x5	Samtec	HTSW-150-08-G-D	HDR_THVT_2X5_100
10	2	L3,L12	560u	Bourns	SRR1208-561KL	SRR1208
11	2	L4,L9	100u	Bourns	SDR0603-101KL	SDR0603
12	2	L5,L13	1m	Bourns	SDR1030-102K	SDR1030
13	2	L7,L14	560u	Bourns	SDR0805-561KL	SDR0805
14	2	L11,L15	680u	Bourns	SDR7030-681K	SDR7030
15	1	P1	Supply VCC	Emerson Network Pow	108-0740-001	JACK_THVT_BANANA_500DIA
16	1	P2	Supply GND	Emerson Network Pow	108-0740-001	JACK_THVT_BANANA_500DIA
17	1	P3	Bus VCC	Emerson Network Pow	108-0740-001	JACK_THVT_BANANA_500DIA
18	1	P4	Bus GND	Emerson Network Pow	108-0740-001	JACK_THVT_BANANA_500DIA
19	1	R1	120	Any	Any (1% Tolerance)	0402
20	2	R2,R3	10k	Any	Any (1% Tolerance)	0402
21	1	R4	450	Any	Any (1% Tolerance)	0402
22	1	R5	50	Any	Any (1% Tolerance)	0402
23	1	U1	DNI	Texas Instruments	SN65HVD75DR	SOIC-8
24	4	Standoff	HEX STANDOFF 6-32 ALUMINUM 2"	Keystone Electronics	2214	
25	4	Screws	MACHINE SCREW PAN PHILLIPS 6-32	APM Hexseal	R6-32X3/8 2701	

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